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Docket: CS 99 - 065CC  
S/N: 09/442,499



To: Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

From: George O. Saile, Reg. No. 19,572  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject:

Serial No.: 09/442,499	Filed: 11/18/1999
Inventor: Ho	
<b>Title: Plasma Etch Method For Forming Plasma Etched Silicon Layer</b>	
Group Art Unit: 1763	Examiner: Goudreau, G. A.
Attorney Docket: CS 99 - 065CC	

#### RESPONSE TO PATENT OFFICE ACTION

Dear Sir:

In response to the office action dated 10/23/2003 and to the Notice of Non-Compliant Amendment mailed February 23, 2004 please consider the following remarks:

#### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450, on March 23, 2004.

Signature/Date

Stephen B. Ackerman  
Reg. No. 37,761

**Charge to Deposit Account**

The Commissioner is hereby authorized to charge payment of the fee of \$\_\_\_\_\_ associated with this communication, or credit any overpayment, to Deposit Account No. 19-0033. The Commissioner is also authorized to charge any additional fee under 37 CFR §1.16 and 1.17 to this Deposit Account. A duplicate copy of this sheet is enclosed. The Commissioner is hereby authorized to charge payment of any additional fees involved with added Claims and the like to Deposit Account No. 19-0033.

Respectively submitted,

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Date

George O. Saile; or

Stephen B. Ackerman